



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20324FGeneric Copy

Issue Date: 16-Dec-2013

TITLE: Assembly and Test site transfer from Kanto Sanyo Semiconductors Co., Ltd to ON Semiconductor SSMP Philippines Corporation (Group 07)

PROPOSED FIRST SHIP DATE: 30-Jan-2015

AFFECTED CHANGE CATEGORY(S): Assembly and Test site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or
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NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

As a part of restructuring of semiconductor production infrastructure, Hanyu plant of Kanto Sanyo Semiconductors Co., Ltd will be closed at the end of June, 2014 and have been started preparation for end of production.

In order to continue supply of applicable products under this condition, the products and the equipments will be transferred to ON Semiconductor SSMP Philippines Corporation.

The materials and package outline of these products will remain identical. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.



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QUALIFICATION PLAN:

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Test Items	Test Condition	Test Time
Temperature Humidity Bias *	Ta=85degC, RH=85%, Vcc=Recommended	1000hrs
Temperature Humidity Storage *	Ta=85degC, RH=85%	1000hrs
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC(30min)	100Cycles
Pressure Cooker *	Ta=121degC, RH=100%, 205kPa	100hrs
High Temperature Storage	Ta=150degC	1000hrs
Resistance to Soldering heat (Reflow soldering : THD)	260degC, 10s	1time
Resistance to Soldering heat (Reflow soldering : SMD)	255degC, 10s(Peak260degC)	2times
Solderability	245degC, 3s(with Flux) Soldering area, 95% over (Sn-3.0Ag-0.5Cu)	1time

Notes:

The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD

Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.

Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

List of affected General Parts:

LC75841PE-H
LC75841PES-H
LC75842E-E
LC75842EHS-E
LE25FW406ATT-TLM-H-D

List of affected Customer Specific Parts:

LC75841PEH-UGN-TFM-H
LC75841PEHUGN-TH
LC75841PES-UNS-TLM-H